Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4965	quartz with SiO\$6	US-PGPUB; USPAT	OR	ON	2005/02/17 22:36
S2	244	S1 and "385"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2005/02/17 15:57
<b>S</b> 3	111	(upper adj1 clad\$6) with (lower\$6 adj1 clad\$6) with ("same" or similar\$6) with material	US-PGPUB; USPAT	OR	ON	2005/02/17 17:26
S4	. 27	(upper adj1 clad\$6) with (lower\$6 adj1 clad\$6) with differ\$6 near2 material\$6	US-PGPUB; USPAT	OR	ON	2005/02/17 17:40
S5	15	(reflow\$6 or "re-flow"\$6) and (CVD) and (waveguid\$6 or (wave adj1 guid\$6)) and (385/130.ccls. or 385/132.ccls. or 385/131.ccls. or 385/129.ccls.) and dop\$6	US-PGPUB; USPAT	OR	ON	2005/02/17 17:44
S6	1	"20020136518" and material\$6	US-PGPUB; USPAT	OR	ON	2005/05/27 18:34
S7	1	"20020136518" and similar\$6	US-PGPUB; USPAT	OR	ON	2005/02/18 11:46
S8	0	"6864114".pn.	US-PGPUB; USPAT	OR	ON	2005/02/18 11:46
S9	0	"6864114".pn.	US-PGPUB; USPAT	OR	ON	2005/02/18 11:47
S10	1260	dry with etch\$6 with chemical with polish\$6	US-PGPUB; USPAT	OR	ON	2005/05/05 08:14
S11	1043	dry adj1 etch\$6 with chemical near2 polish\$6	US-PGPUB; USPAT	OR	ON	2005/05/27 19:25
S12	1035	dry adj1 etch\$6 with chemical with mechanical with polish\$6	US-PGPUB; USPAT	OR	ON	2005/05/05 08:15
S13	990	dry adj1 etch\$6 with chemical adj1 mechanical adj1 polish\$6	US-PGPUB; USPAT	OR	ON	2005/05/05 08:16
S14	18	dry adj1 etch\$6 with chemical adj1 mechanical adj1 polish\$6 and "385"/\$.ccls.	US-PGPUB; USPAT	OR	ON	2005/05/05 08:16
S15	0	"20020136518" and (chemic\$6 with etch\$6)	US-PGPUB; USPAT	OR	ON	2005/05/27 18:34
S16	0	"20020136518" and (chemical\$6 with etch\$6)	US-PGPUB; USPAT	OR	ON	2005/05/27 18:34
S17	1	"20020136518"	US-PGPUB; USPAT	OR	ON	2005/05/27 18:34
S18	1	"20020136518" and (chemical\$6 same etch\$6)	US-PGPUB; USPAT	OR	ON	2005/05/27 18:36
S19	1	"20020136518" and (chemical\$6 same polish\$6)	US-PGPUB; USPAT	OR	ON	2005/05/27 18:57

S20	1	"20020136518" and flush\$6	US-PGPUB; USPAT	OR	ON	2005/05/27 18:58
S21	190	etch\$6 and substrate and hori.in.	US-PGPUB; USPAT	OR	ON	2005/05/27 19:26
S22	0	etch\$6 and substrate and hori.in. and shinobu.in.	US-PGPUB; USPAT	OR	ON	2005/05/27 19:26
S23	1	etch\$6 and substrate and hori.in. and Akihiro	US-PGPUB; USPAT	OR	ON	2005/05/27 19:27
S24	80	etch\$6 and substrate and shinobu. in.	US-PGPUB; USPAT	OR	ON	2005/05/27 19:28
S25	1960	etch\$6 and substrate and sato.in.	US-PGPUB; USPAT	OR	ON	2005/05/27 19:28
S26	0	etch\$6 and substrate and sato.in. with shinobu	US-PGPUB; USPAT	OR	ON	2005/05/27 19:28
S27	3	etch\$6 and substrate and sato.in. and shinobu	US-PGPUB; USPAT	OR	ON	2005/05/27 19:29